# Ultra-Small Dual Single Pole, Single Throw Analog Switch with Over Voltage Tolerance

The NLAS2066 is a Dual SPST (Single Pole, Single Throw) Analog Switch high performance version of the popular NLAS323. Packaged in the ultra-small US8 package. It is designed as a general analog/digital switch and can also be used to isolate USB ports.

## Features

- Same Pinout as the Popular NLAS323
- Excellent Performance Maximum RDS<sub>ON</sub> 15  $\Omega$  at 3.0 V
- Matching Between the Switches  $\pm 1.5 \Omega$  at 3.0 V
- 1.65 V to 5.5 V Operating Range
- Lower Threshold Voltages for LVTTL/CMOS Levels
- Ultra-Low Charge Injection  $\leq 4.8 \text{ pC}$  at 3.0 V
- Low Standby Power  $I_{CC} = 1.0 \text{ nA} \text{ (max)} @ T_A = 25^{\circ}C$
- CMOS Level Compatibility
- OVT\* (Pins 1, 3, 5, and 7) These Pins may be Subjected to 0 to +7.0 V, Regardless of Operating Voltage
- Allows a Short from USB Line without Damage to the Device
- This is a Pb-Free Device\*

### **Typical Applications**

- USB Isolation
- Cell Phones
- PDAs
- MP3s Digital Still Cameras

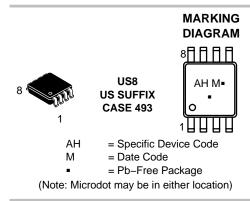
#### **Important Information**

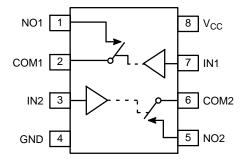
- ESD Protection: Human Body Model; > 1500 V Machine Model; > 200 V
- Latch-Up Maximum Rating: 200 mA



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### **PIN ASSIGNMENT**

Pin	Function	Οντ
1	NO1	Yes
2	COM1	-
3	IN2	Yes
4	GND	-
5	NO2	Yes
6	COM2	-
7	IN1	Yes
8	V <sub>CC</sub>	_

#### **FUNCTION TABLE**

On/Off Enable Input	State of Analog Switch
L	Off
Н	On

- \*Over Voltage Tolerance (OVT) enables pins to function outside (higher) of their operating voltages, with no damage to the devices or to signal integrity.
- \*\*For additional information on our Pb–Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

#### **ORDERING INFORMATION**

See detailed ordering and shipping information in the package dimensions section on page 8 of this data sheet.

## MAXIMUM RATINGS

Symbol	Ratii	ng	Value	Unit
V <sub>CC</sub>	DC Supply Voltage		-0.5 to +7.0	V
VI	DC Input Voltage	-0.5  to  +7.0 -0.5 to V <sub>CC</sub>	V	
Vo	DC Output Voltage		-0.5 to +7.0	V
l <sub>IK</sub>	DC Input Diode Current	V <sub>I</sub> < GND	- 50	mA
I <sub>OK</sub>	DC Output Diode Current	- 50	mA	
l <sub>O</sub>	DC Output Sink Current	±50	mA	
I <sub>CC</sub>	DC Supply Current per Supply Pin	±100	mA	
I <sub>GND</sub>	DC Ground Current per Ground Pin		±100	mA
T <sub>STG</sub>	Storage Temperature Range		-65 to +150	°C
TL	Lead Temperature, 1 mm from Case for 1	0 Seconds	260	°C
TJ	Junction Temperature under Bias		+ 150	°C
$\theta_{JA}$	Thermal Resistance (Note 1)		250	°C/W
PD	Power Dissipation in Still Air at 85°C		250	mW
MSL	Moisture Sensitivity		Level 1	-
F <sub>R</sub>	Flammability Rating	Oxygen Index: 28 to 34	UL 94 V–0 @ 0.125 in	-
V <sub>ESD</sub>	ESD Withstand Voltage	Human Body Model (Note 2) Machine Model (Note 3) Charged Device Model (Note 4)	> 1500 > 200 N/A	V

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

1. Measured with minimum pad spacing on an FR4 board, using 10 mm-by-1 inch, 2-ounce copper trace with no air flow

2. Tested to EIA/JESD22-A114-A

3. Tested to EIA/JESD22-A115-A

4. Tested to JESD22-C101-A

## **RECOMMENDED OPERATING CONDITIONS**

Symbol	ol Characteristics			Max	Unit
V <sub>CC</sub>	Positive DC Supply Voltage		1.65	5.5	V
V <sub>IN</sub>	Digital Input Voltage (INx)		GND	5.5	V
V <sub>IO</sub>	Static or Dynamic Voltage Across an Off Switch	GND	V <sub>CC</sub>	V	
V <sub>IS</sub>	Analog Input Voltage NO COM		GND GND	5.5 V <sub>CC</sub>	V
T <sub>A</sub>	Operating Temperature Range, All Package Types		-55	+125	°C
t <sub>r</sub> , t <sub>f</sub>	Input Rise or Fall Time (Enable Input)	$V_{CC} = 3.3 V \pm 0.3 V$ $V_{CC} = 5.0 V \pm 0.5 V$	0 0	100 20	ns/V

Functional operation above the stresses listed in the Recommended Operating Ranges is not implied. Extended exposure to stresses beyond the Recommended Operating Ranges limits may affect device reliability.

# DEVICE JUNCTION TEMPERATURE VS. TIME TO 0.1% BOND FAILURES

Junction Temperature °C	Time, Hours	Time, Years
80	1,032,200	117.8
90	419,300	47.9
100	178,700	20.4
110	79,600	9.4
120	37,000	4.2
130	17,800	2.0
140	8,900	1.0

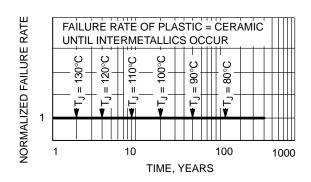


Figure 1. Failure Rate vs. Time Junction Temperature

## DC CHARACTERISTICS - Digital Section (Voltages Referenced to GND)

				G	uaranteed Max Lim	nit	
Symbol	Parameter	Condition	V <sub>cc</sub>	25°C	–40 to 85°C	–55 to <125°C	Unit
V <sub>IH</sub>	Minimum High– Level Input Voltage, Enable Inputs		$\begin{array}{c} 2.3 \pm 10\% \\ 2.7 \pm 10\% \\ 3.0 \pm 10\% \\ 5.0 \pm 10\% \end{array}$	V <sub>CC</sub> x 0.55 V <sub>CC</sub> x 0.55 V <sub>CC</sub> x 0.55 V <sub>CC</sub> x 0.55	V <sub>CC</sub> x 0.55 V <sub>CC</sub> x 0.55 V <sub>CC</sub> x 0.55 V <sub>CC</sub> x 0.55 V <sub>CC</sub> x 0.55	V <sub>CC</sub> x 0.55 V <sub>CC</sub> x 0.55 V <sub>CC</sub> x 0.55 V <sub>CC</sub> x 0.55 V <sub>CC</sub> x 0.55	V
V <sub>IL</sub>	Maximum Low– Level Input Voltage, Enable Inputs		$\begin{array}{c} 2.3 \pm 10\% \\ 2.7 \pm 10\% \\ 3.0 \pm 10\% \\ 5.0 \pm 10\% \end{array}$	V <sub>CC</sub> x 0.30 V <sub>CC</sub> x 0.30 V <sub>CC</sub> x 0.30 V <sub>CC</sub> x 0.30	V <sub>CC</sub> x 0.30 V <sub>CC</sub> x 0.30 V <sub>CC</sub> x 0.30 V <sub>CC</sub> x 0.30	V <sub>CC</sub> x 0.30 V <sub>CC</sub> x 0.30 V <sub>CC</sub> x 0.30 V <sub>CC</sub> x 0.30 V <sub>CC</sub> x 0.30	V
I <sub>IN</sub>	Maximum Input Leakage Current, Enable Inputs	$V_{IN} = 5.5 V \text{ or GND}$	0 V to 5.5 V	<u>+</u> 0.1	<u>+</u> 1.0	<u>+</u> 1.0	μΑ
I <sub>CC</sub>	Maximum Quies- cent Supply Current (per package)	Enable and $V_{IS} = V_{CC}$ or GND	5.5	1.0	1.0	2.0	μΑ

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

DC ELECTRICAL	<b>CHARACTERISTICS</b>	– Analog Section
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				G	uaranteed Max Lir	nit	
Symbol	Parameter	Condition	v <sub>cc</sub>	25°C	–40 to 85°C	–55 to <125°C	Unit
R <sub>ON</sub>	Maximum On	$V_{IN} = V_{IH}$ $I_s = 8 \text{ mA}$	2.3	50	54	54	Ω
	Resistance	$V_{IS} = V_{CC}$ to GND $I_s = 8$ mA	2.7	20	24	24	
		I <sub>s</sub> = 24 mA	3.0	15	19	19	
		I <sub>s</sub> = 32 mA	4.5	7	11	11	
		(Figures 2 and 3)					
R <sub>FLAT(ON)</sub>	On Resistance	$V_{IN} = V_{IH}$ $I_s = 8 \text{ mA}$	2.3	60	60	60	Ω
	Flatness	$V_{IS} = 0$ to $V_{CC}$ $I_s = 8$ mA	2.7	24	24	24	
		I <sub>s</sub> = 24 mA	3.0	13.5	13.5	13.5	
		I <sub>s</sub> = 32 mA	4.5	3.0	3.0	3.0	
		(Figure 5)					
$\Delta R_{ON}$	On Resistance	V <sub>IS</sub> = 1.4 V	2.3	1.3	1.3	1.3	Ω
	Match Between	V <sub>IS</sub> = 1.6 V	2.7	1.4	1.4	1.4	
	Channels	V <sub>IS</sub> = 1.8 V	3.0	1.5	1.5	1.5	
		V <sub>IS</sub> = 2.7 V	4.5	2.0	2.0	2.0	
		(Figures 4, 5 and 6)					
I <sub>NO(OFF)</sub>	Off Leakage Current	$\begin{split} V_{\text{IN}} &= V_{\text{IL}} \\ V_{\text{NO}} &= 1.0 \text{ V},  V_{\text{COM}} = 4.5 \text{ V} \\ \text{or} \\ V_{\text{COM}} &= 1.0 \text{ V} \text{ and }  V_{\text{NO}}  4.5 \text{ V} \end{split}$	5.5	1.0	10	100	nA
I <sub>COM(OFF)</sub>	Off Leakage Current	$V_{IN} = V_{IL}$ $V_{NO} = 4.5 V \text{ or } 1.0 V$ $V_{COM} = 1.0 V \text{ or } 4.5 V$	5.5	1.0	10	100	nA

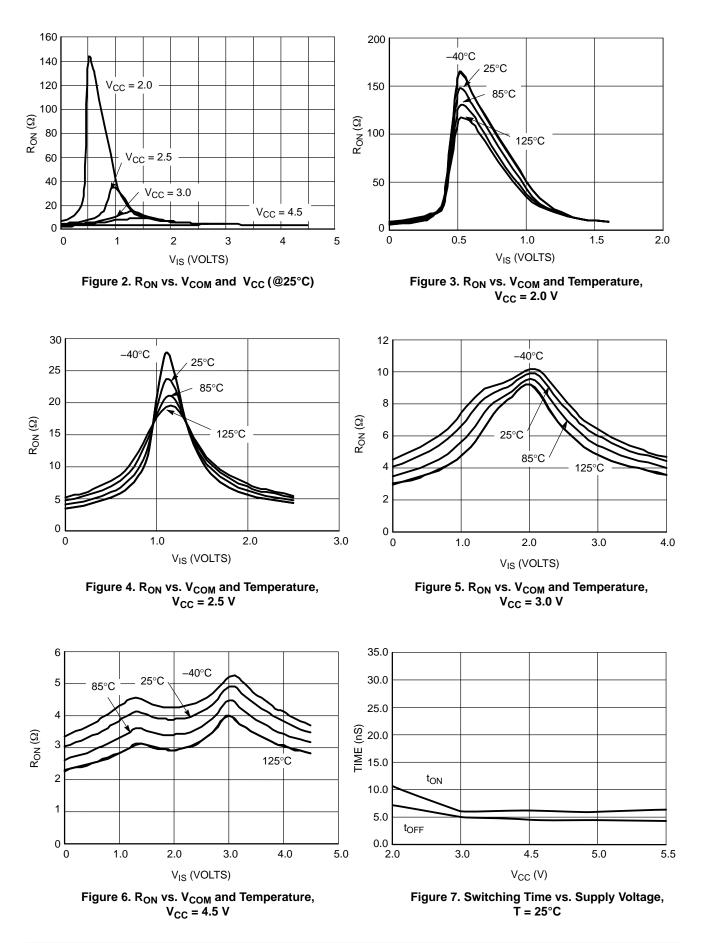
# **AC ELECTRICAL CHARACTERISTICS** (Input $t_r = t_f = 3.0 \text{ ns}$ )

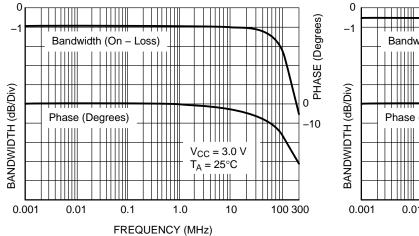
						G	uarant	eed M	ax Lin	nit			
			v <sub>cc</sub>		25°C		-4	0 to 85	5°C	-55	to <12	25°C	
Symbol	Parameter	Condition	(V)	Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	Unit
t <sub>ON</sub>	Turn–On Time	$R_L$ = 300 Ω, $C_L$ = 35 pF (Figures 7, 14 and 15)	2.3 2.7 3.0 4.5		8 4 3 2	9 5 4 3			10 7 6 5			10 7 6 5	ns
t <sub>OFF</sub>	Turn-Off Time	$R_L$ = 300 $\Omega$ , $C_L$ = 35 pF (Figures 7, 14 and 15)	2.3 2.7 3.0 4.5		8 6 5 4	10 8 7 6			11 9 8 7			11 9 8 7	ns

		Typical @ 25°C, V <sub>CC</sub> = 5.0 V	Unit
C <sub>IN</sub>	Maximum Input Capacitance, Select Input	3.0	pF
C <sub>NO</sub> or C <sub>NC</sub>	Analog I/O (Switch Off)	10	
C <sub>COM(OFF)</sub>	Common I/O (Switch Off)	10	
C <sub>COM(ON)</sub>	Feedthrough (Switch Off)	10	

Symbol	Parameter	Condition	V <sub>CC</sub> (V)	Typical 25°C	Unit
BW	Maximum On–Channel –3.0 dB Bandwidth or Minimum Frequency Response	V <sub>IS</sub> = 0 dBm (Figure 8 and 9)	2.3 2.7 3.0 4.5	102 175 180 186	MHz
V <sub>ONL</sub>	Maximum Feed–Through On Loss	V <sub>IS</sub> = 0 dBm @ 10 kHz (Figure 8 and 9)	2.3 2.7 3.0 4.5	-2.2 -0.9 -0.8 -0.4	dB
V <sub>ISO</sub>	Off-Channel Isolation	f = 100 kHz V <sub>IS</sub> = 1.0 V RMS (Figure 10 and 11)	2.3 2.7 3.0 4.5	-73 -74 -74 -75	dB
Q	Charge Injection Enable Input to Common I/O	$V_{IS} = V_{CC}$ to GND, $F_{IS} = 20$ kHz (Figure 12)	3.0 5.5	4.8 7.4	рС
THD	Total Harmonic Distortion TDH + Noise	$F_{IS}$ = 10 Hz to 100 kHz, R <sub>L</sub> = Rgen = 600 $\Omega$ , C <sub>L</sub> = 50 pF (Figure 13)	3.0 5.5	0.19 0.06	%

# ADDITIONAL APPLICATIONS CHARACTERISTICS (Voltage Reference to GND Unless Noted)







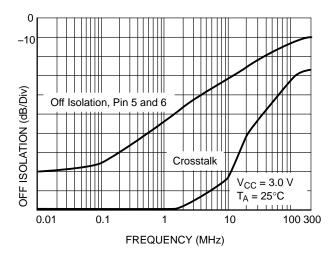
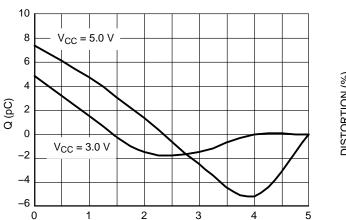


Figure 10. Off Isolation and Crosstalk





V<sub>COM</sub> (V)

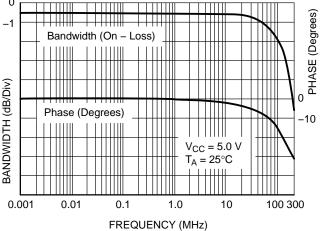


Figure 9. ON Channel Bandwidth and Phase Shift Over Frequency

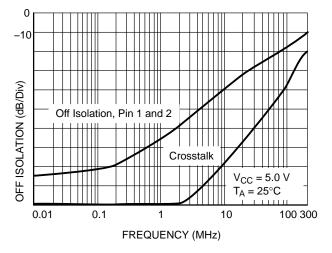


Figure 11. Off Isolation and Crosstalk

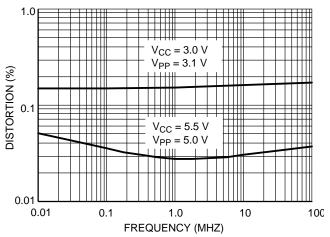
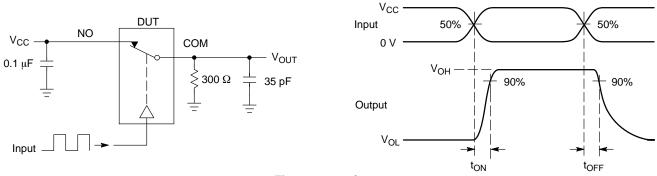
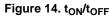
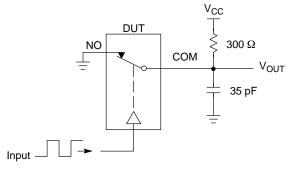


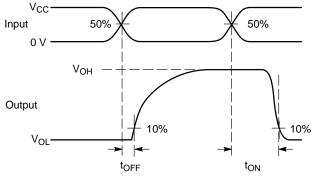
Figure 13. THD vs. Frequency

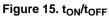
## TIMING INFORMATION











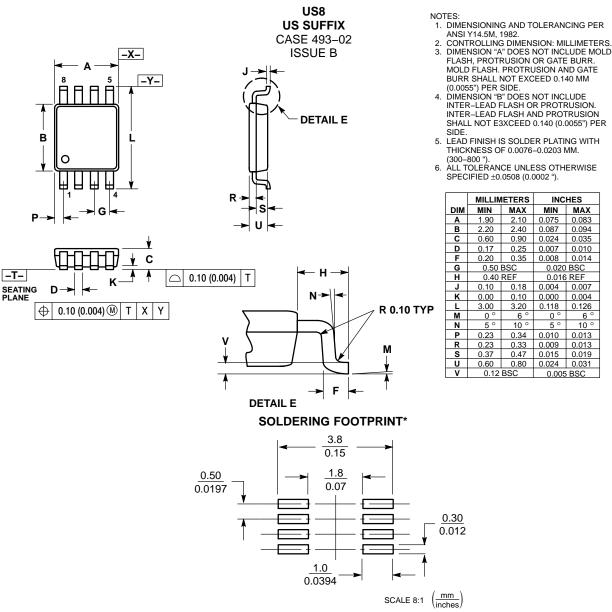
V <sub>cc</sub>	VMI
2.0 V	1.0 V
3.0 V	1.5 V
4.5 V	1.5 V

## **DEVICE ORDERING INFORMATION**

	Device Nomenclature					
Device	Circuit Indicator	Technology	Device Function	Package Suffix	Package Type	Shipping <sup>†</sup>
NLAS2066USG	NL	AS	2066	US	US8 (Pb–Free)	3,000 / Tape & Reel
NLAS2066UST3G	NL	AS	2066	UST3	US8 (Pb–Free)	10,000 / Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

#### PACKAGE DIMENSIONS



\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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